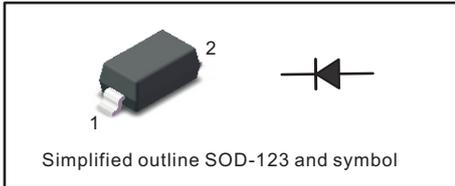


### PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



### FEATURES

- Total power dissipation: Max. 500mW.
- Wide zener reverse voltage range 5.1V
- Small plastic package suitable for surface mounted design.
- Tolerance approximately  $\pm 5\%$

### MECHANICAL DATA

- Case: SOD-123
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 16mg 0.00056oz

### Absolute Maximum Ratings And Characteristics ( Ta = 25 °C )

Parameter	Symbol	Value	Unit
Power Dissipation	$P_{tot}$	500	mW
Forward Voltage at $I_F = 10\text{ mA}$	$V_F$	0.9	V
Typical thermal resistance junction to ambient <sup>(1)</sup>	$R_{\theta JA}$	340	$^{\circ}\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150	$^{\circ}\text{C}$

(1) Thermal resistance from junction to ambient at P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper areas pads.

Fig.1 Maximum Continuous Power Derating

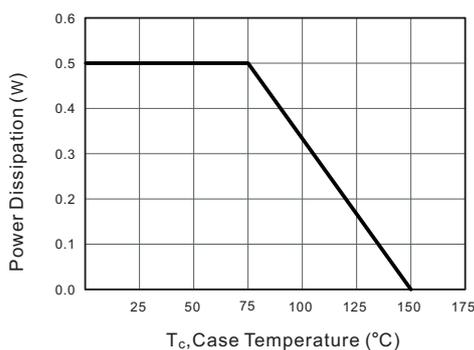
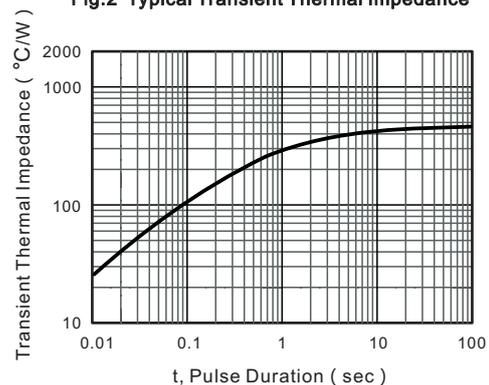


Fig.2 Typical Transient Thermal Impedance



### Characteristics at Ta = 25°C

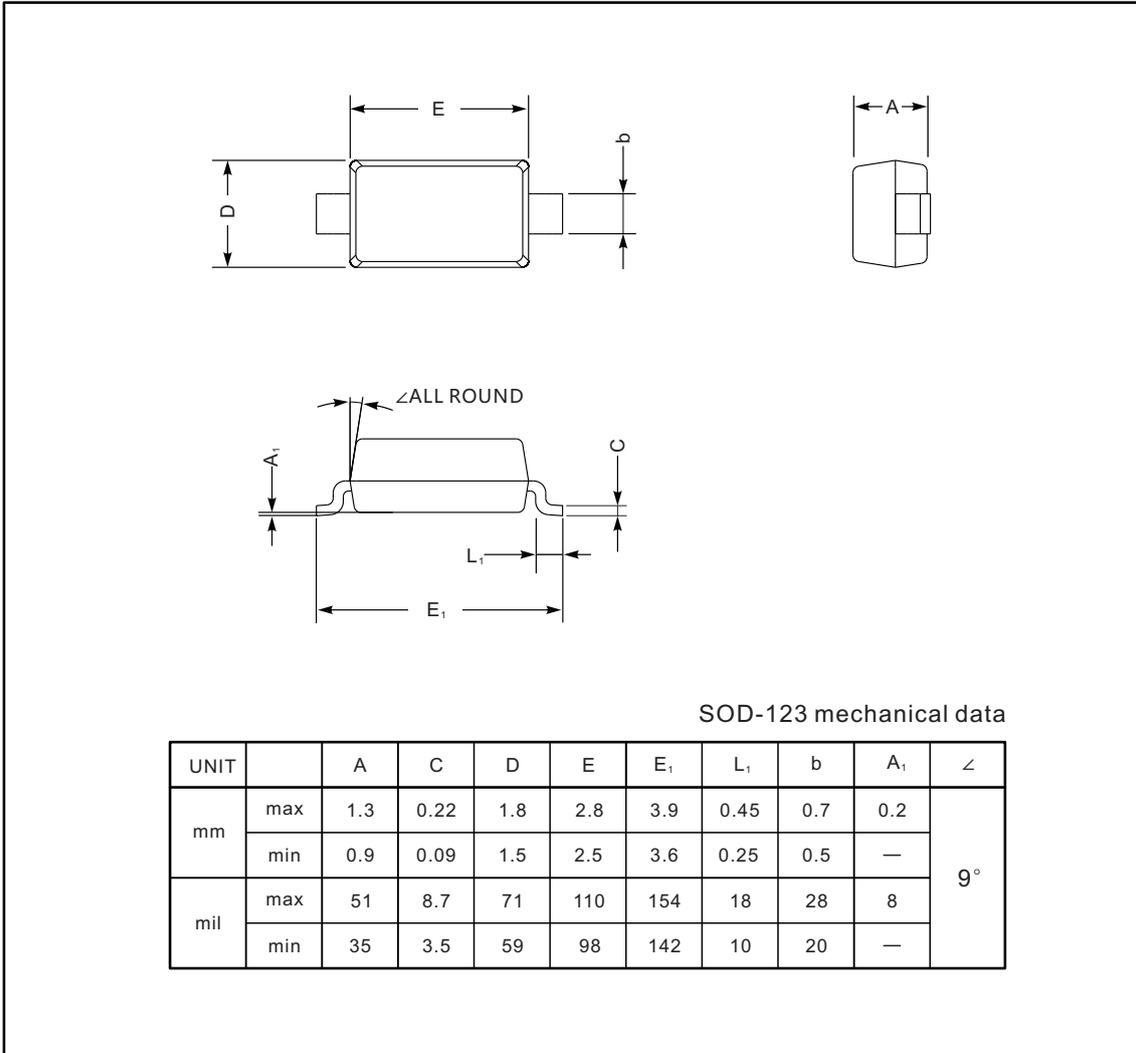
Type	Marking	Zener Voltage Range <sup>(1)</sup>			$I_{ZT}$ (mA)	Dynamic Impedance	Reverse Current	
		$V_{ZT}$ (at $I_{ZT}$ )				$Z_{ZT}$ (at $I_{ZT}$ )	$I_R$	at $V_R$
		Min (V)	Nom (V)	Max (V)		Max (Ω)	Max (μA)	(V)
MMSZ5231B	E1	4.8	5.1	5.4	5	130	2	1.5

(1)  $V_{ZT}$  is tested with pulses (20 ms)

**PACKAGE OUTLINE**

Plastic surface mounted package; 2 leads

SOD-123



**The recommended mounting pad size**

